

Single-chip Type with Built-in FET Switching Regulators

Output 1.5A or Less

High-efficiency Step-down Switching Regulator with Built-in Power MOSFET



BD9123MUV

No.11027EAT38

●Description

ROHM's high efficiency step-down switching regulator BD9123MUV is a power supply designed to produce a low voltage including 0.85 to 1.2 volts from 5.5/3.3 volts power supply line. Offers high efficiency with our original pulse skip control technology and synchronous rectifier. Employs a current mode control system to provide faster transient response to sudden change in load.

●Features

- 1) Offers fast transient response with current mode PWM control system.
- 2) Offers highly efficiency for all load range with synchronous rectifier (Nch/Pch FET) and SLLM (Simple Light Load Mode)
- 3) Incorporates output voltage inside control function.(3 bit)
- 4) Incorporates PGOOD function.
- 5) Incorporates soft-start function.
- 6) Incorporates thermal protection and ULVO functions.
- 7) Incorporates short-current protection circuit with time delay function.
- 8) Incorporates shutdown function $I_{cc}=0\mu A$ (Typ.)
- 9) Employs small surface mount package: VQFN016V3030

●Applications

Power supply for LSI including DSP, Micro computer and ASIC

●Absolute maximum ratings (Ta=25°C)

Parameter	Symbol	Ratings	Unit
VCC Voltage	Vcc	-0.3~+7 * ¹	V
PVCC Voltage	PVcc	-0.3~+7 * ¹	V
EN,SW,ITH Voltage	EN, SW, ITH	-0.3~+7	V
Logic input voltage	VID<2:0>	-0.3~+7	V
Power Dissipation 1	Pd1	0.27 * ²	W
Power Dissipation 2	Pd2	0.62 * ³	W
Power Dissipation 3	Pd3	1.77 * ⁴	W
Power Dissipation 4	Pd4	2.66 * ⁵	W
Operating temperature range	Topr	-40~+95	°C
Storage temperature range	Tstg	-55~+150	°C
Maximum junction temperature	Tj	+150	°C

*¹ Pd should not be exceeded.

*² IC only

*³ 1-layer. mounted on a 74.2mm × 74.2mm × 1.6mm glass-epoxy board, occupied area by copper foil : 10.29mm²

*⁴ 4-layer. mounted on a 74.2mm × 74.2mm × 1.6mm glass-epoxy board, 1st and 4th copper foil area : 10.29mm², 2nd and 3rd copper foil area : 5505mm²

*⁵ 4-layer. mounted on a 74.2mm × 74.2mm × 1.6mm glass-epoxy board, occupied area by copper foil : 5505mm², in each layers

● **Operating Conditions** (Ta=-40~+95°C)

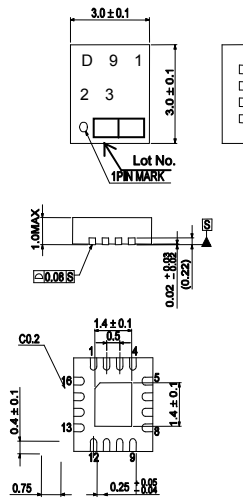
Parameter	Symbol	Ratings			Unit
		Min.	Typ.	Max.	
Power Supply Voltage	V _{CC}	2.7	3.3	5.5	V
	PV _{CC}	2.7	3.3	5.5	V
EN Voltage	V _{EN}	0	-	V _{CC}	V
Logic input voltage	VID<2:0>	0	-	5.5	V
Output voltage Setting Range	V _{OUT}	0.85	-	1.2	V
SW average output current	I _{SW}	-	-	1.2 ^{*6}	A

*6 Pd should not be exceeded.

● **Electrical Characteristics** (Ta=25°C V_{CC}=PV_{CC}=5V, EN=V_{CC}, VID<2>=VID<1>=VID<0>=0V), unless otherwise specified.)

Parameter	Symbol	Limits			Unit	Conditions
		Min.	Typ.	Max.		
Standby current	I _{STB}	-	0	10	μA	EN=GND
Active current	I _{CC}	-	300	500	μA	
EN Low voltage	V _{ENL}	-	GND	0.8	V	Standby mode
EN High voltage	V _{ENH}	2.0	V _{CC}	-	V	Active mode
EN input current	I _{EN}	-	5	10	μA	V _{EN} =5V
VID Low voltage	V _{VIDL}	-	GND	0.8	V	
VID High voltage	V _{VIDH}	2.0	V _{CC}	-	V	
VID input current	I _{VID}	-	5	10	μA	V _{VID} =5V
Oscillation frequency	F _{OSC}	0.8	1	1.2	MHz	
Pch FET ON resistance	R _{ONP}	-	0.35	0.60	Ω	PV _{CC} =5V
Nch FET ON resistance	R _{ONN}	-	0.25	0.50	Ω	PV _{CC} =5V
Output voltage	V _{OUT}	0.98	1.0	1.02	V	VID<2:0>=(0,0,0)
ITH sink current	I _{THSI}	25	50	-	μA	V _{OUT} =1.2V
ITH source current	I _{THSO}	25	50	-	μA	V _{OUT} =0.8V
UVLO threshold voltage	V _{UVLO1}	2.4	2.5	2.6	V	V _{CC} =5V→0V
UVLO release voltage	V _{UVLO2}	2.425	2.55	2.7	V	V _{CC} =0V→5V
Power Good Threshold	V _{PGOOD1}	70	75	80	%	V _{OUT} →0V
Power Good Release	V _{PGOOD2}	85	90	95	%	0V→V _{OUT}
Power Good Delay	T _{PG}	2.5	5	10	ms	
PGOOD ON Resistance	R _{ONPG}	-	140	280	Ω	
Soft start time	T _{SS}	0.4	0.8	1.6	ms	
Timer latch time	T _{LATCH}	1	2	4	ms	
Output Short circuit threshold Voltage	V _{SCP}	-	V _{OUT} × 0.5	V _{OUT} × 0.7	V	V _{OUT} →0V

●Package outline, SYMBOLS
【BD9123MUV】



VQFN016V3030 (Unit:mm)
Fig.1 BD9123MUV Package outline

●Block Diagram, Application Circuit

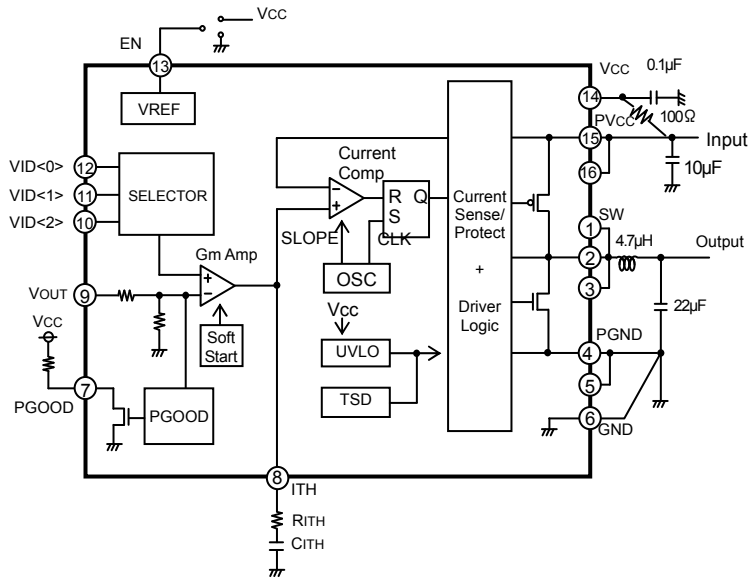


Fig.2 BD9123MUV Block Diagram

●Pin No. & function table

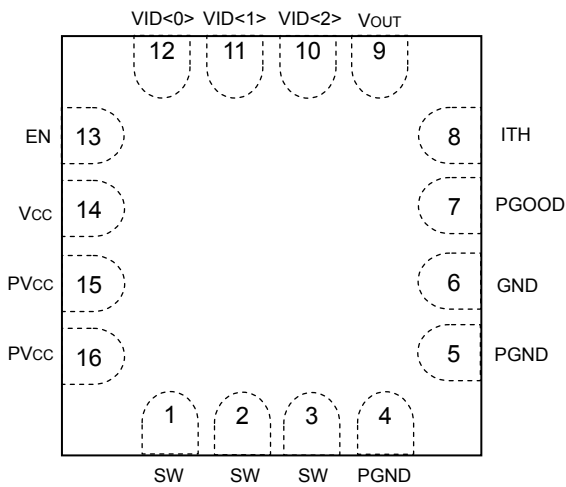


Fig 3 Top View

Pin No.	Pin name	Function
1	SW	Pch/Nch FET drain output pin
2		
3		
4	PGND	Nch FET source pin
5		
6	GND	Ground
7	PGOOD	Power Good pin
8	ITH	Gm Amp output pin/Connected phase compensation capacitor
9	VOUT	Output voltage pin
10	VID<2>	Output voltage control pin<2>
11	VID<1>	Output voltage control pin<1>
12	VID<0>	Output voltage control pin<0>
13	EN	Enable pin(High Active)
14	VCC	VCC power supply input pin
15	PVCC	Pch FET source pin
16		

●Characteristics data

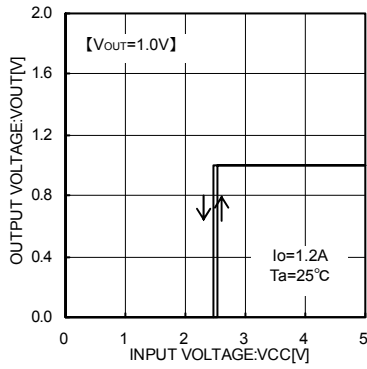


Fig.4 Vcc-Vout

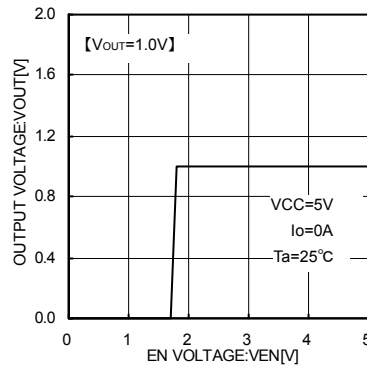


Fig.5 VEN - VOUT

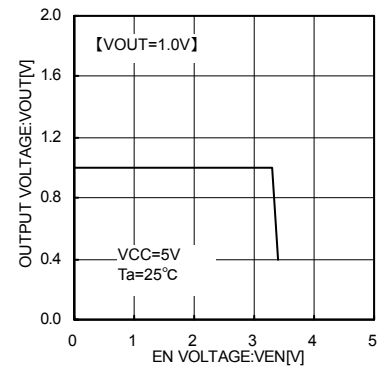


Fig.6 IOUT-VOUT

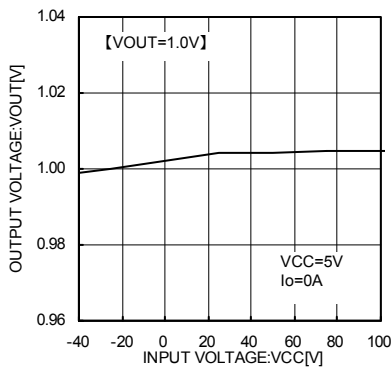


Fig.7 Ta-VOUT

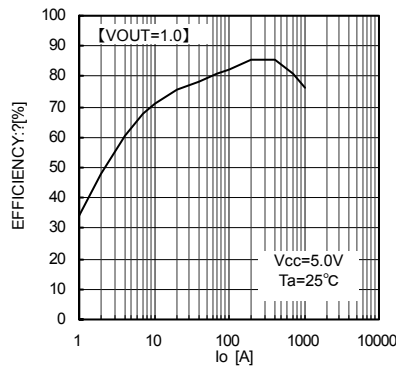


Fig.8 Efficiency

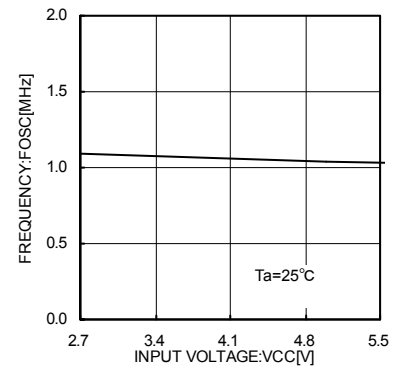
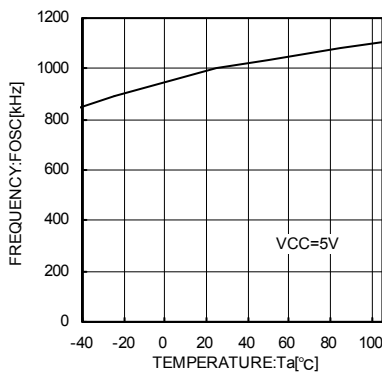
Fig.9 Power supply voltage-
Operating frequency

Fig.10 Ta-Fosc

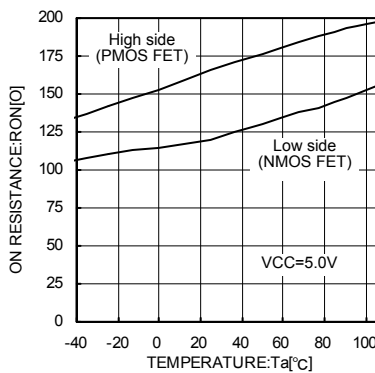


Fig.11 Ta-RONN, RONP

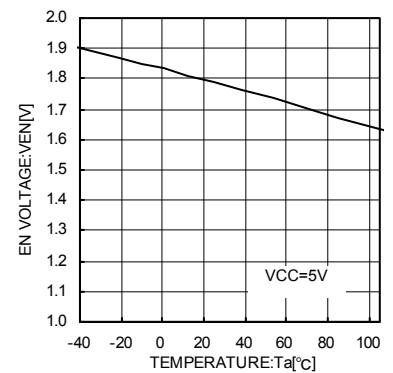


Fig.12 Ta-VEN

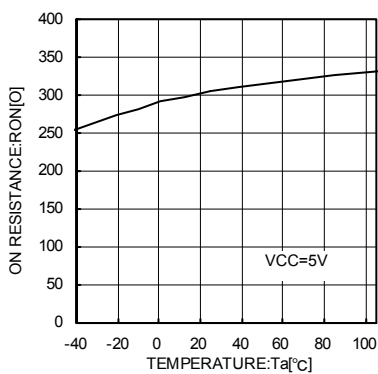


Fig.13 Ta-Icc

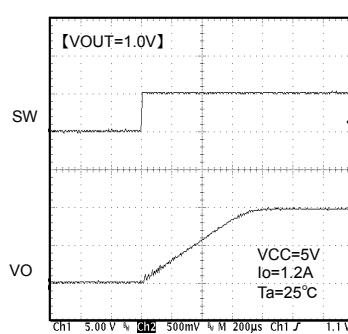


Fig.14 Soft start waveform

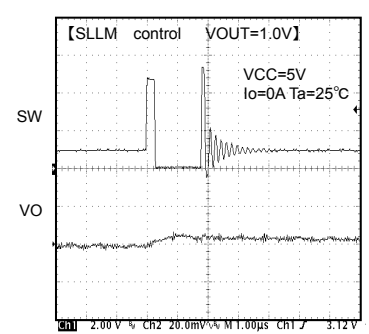


Fig.15 SW waveform Io=0mA

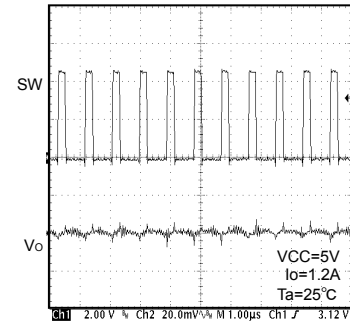


Fig.16 SW waveform Io=1.2A

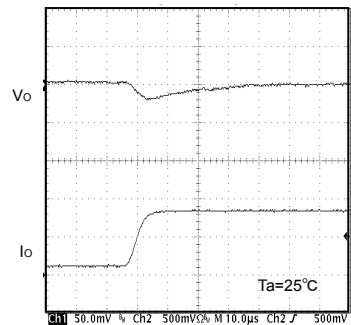


Fig.17 Transient Response
Io=125mA→850mA(2μA)

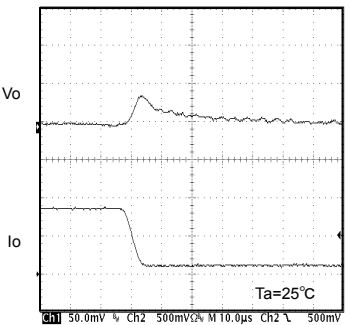


Fig.18 Transient Response
Io=850mA→125mA(2μA)

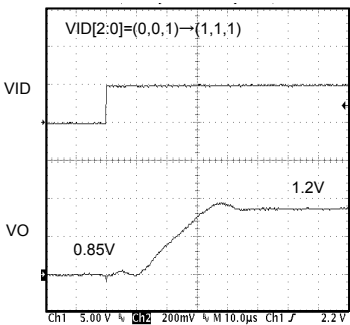


Fig.19 BIT CHANCE RESPONSE

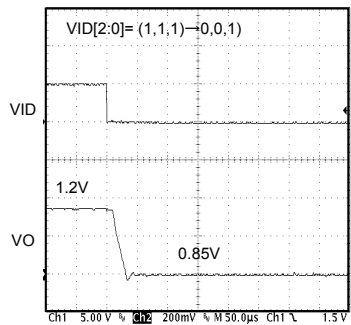


Fig.20 BIT CHANCE RESPONSE

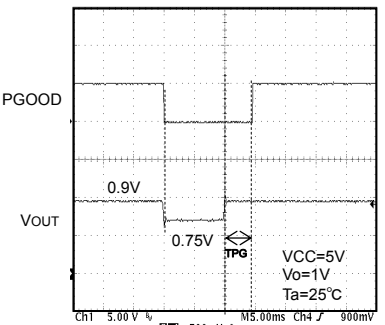
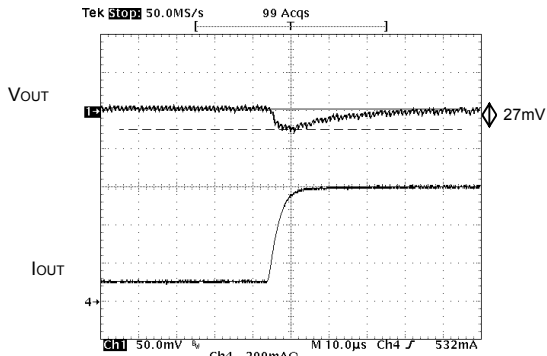


Fig.21 PGOOD Delay

● Information on advantages

Advantage 1: Offers fast transient response with current mode control system.

Conventional product (Load response $I_o=0.1A \rightarrow 0.6A$)



BD9123MUV (Load response $I_o=0.6A \rightarrow 0.1A$)

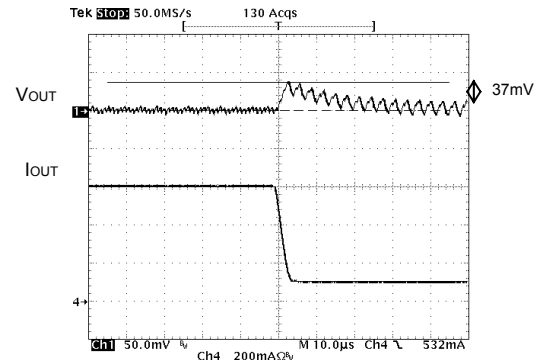


Fig.22 Comparison of transient response

Advantage 2: Offers high efficiency for all load range.

• For lighter load:

Utilizes the current mode control mode called SLLM for lighter load, which reduces various dissipation such as switching dissipation (P_{SW}), gate charge/discharge dissipation, ESR dissipation of output capacitor (P_{ESR}) and on-resistance dissipation (P_{RON}) that may otherwise cause degradation in efficiency for lighter load.

Achieves efficiency improvement for lighter load.

• For heavier load:

Utilizes the synchronous rectifying mode and the low on-resistance MOS FETs incorporated as power transistor.

- { ON resistance of Pch side MOS FET : $0.35m\Omega$ (Typ.)
- { ON resistance of Nch side MOS FET : $0.25m\Omega$ (Typ.)

Achieves efficiency improvement for heavier load.

Offers high efficiency for all load range with the improvements mentioned above.

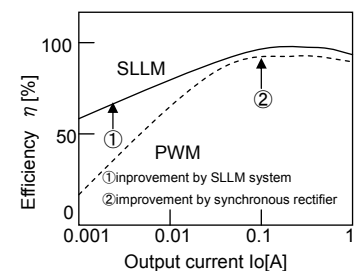


Fig.23 Efficiency

Advantage 3:

- Supplied in smaller package due to small-sized power MOS FET incorporated.

- Output capacitor C_o required for current mode control: $10\mu F$ ceramic capacitor
- Inductance L required for the operating frequency of 1 MHz: $4.7\mu H$ inductor

Reduces a mounting area required.

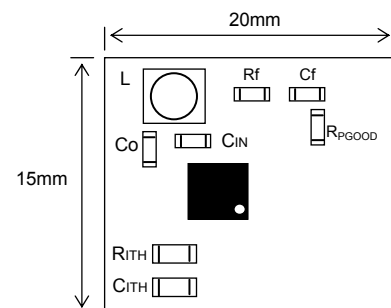
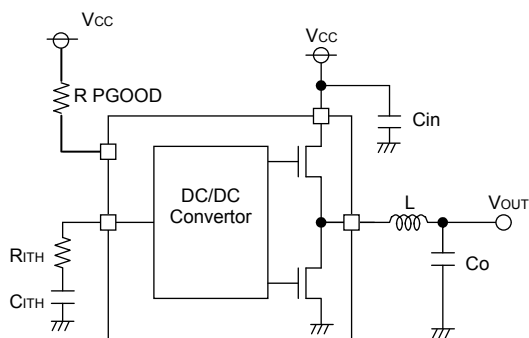


Fig.24 Example application

●Operation

BD9123MUV is a synchronous rectifying step-down switching regulator that achieves faster transient response by employing current mode PWM control system. It utilizes switching operation in PWM (Pulse Width Modulation) mode for heavier load, while it utilizes SLLM (Simple Light Load Mode) operation for lighter load to improve efficiency.

○Synchronous rectifier

It does not require the power to be dissipated by a rectifier externally connected to a conventional DC/DC converter IC, and its P.N junction shoot-through protection circuit limits the shoot-through current during operation, by which the power dissipation of the set is reduced.

○Current mode PWM control

Synthesizes a PWM control signal with a inductor current feedback loop added to the voltage feedback.

• PWM (Pulse Width Modulation) control

The oscillation frequency for PWM is 1 MHz. SET signal from OSC turns ON a Pch MOS FET (while a Nch MOS FET is turned OFF), and an inductor current I_L increases. The current comparator (Current Comp) receives two signals, a current feedback control signal (SENSE: Voltage converted from I_L) and a voltage feedback control signal (FB), and issues a RESET signal if both input signals are identical to each other, and turns OFF the highside MOS FET (while a lowside MOS FET is turned ON) for the rest of the fixed period. The PWM control repeat this operation.

• SLLM (Simple Light Load Mode) control

When the control mode is shifted from PWM for heavier load to the one for lighter load or vice versa, the switching pulse is designed to turn OFF with the device held operated in normal PWM control loop, which allows linear operation without voltage drop or deterioration in transient response during the mode switching from light load to heavy load or vice versa. Although the PWM control loop continues to operate with a SET signal from OSC and a RESET signal from Current Comp, it is so designed that the RESET signal is held issued if shifted to the light load mode, with which the switching is tuned OFF and the switching pulses are thinned out under control. Activating the switching intermittently reduces the switching dissipation and improves the efficiency.

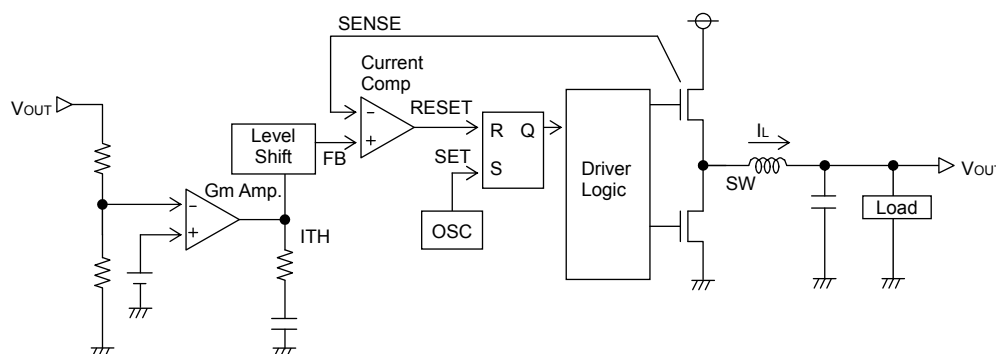


Fig.25 Diagram of current mode PWM control

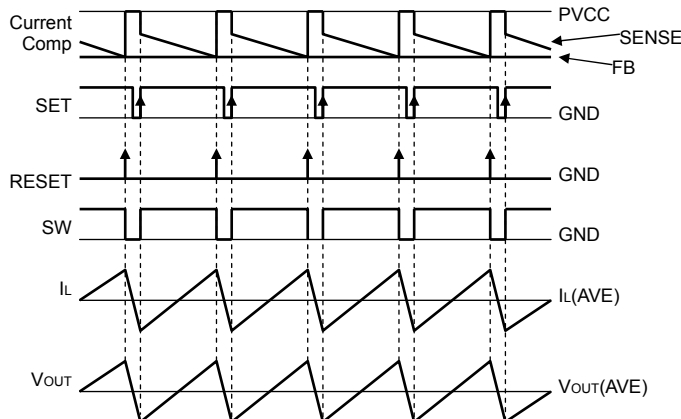


Fig.26 PWM switching timing chart

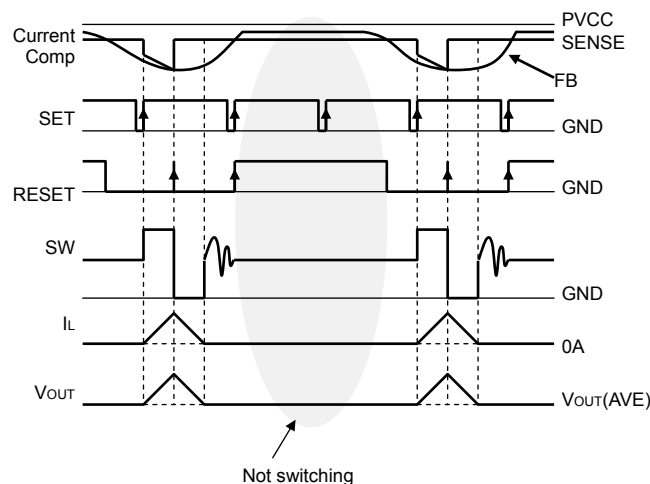


Fig.27 SLLM™ switching timing chart

●Description of operations

• Soft-start function

EN terminal shifted to "High" activates a soft-starter to gradually establish the output voltage with the current limited during startup, by which it is possible to prevent an overshoot of output voltage and an inrush current.

The inclination of standing up is different and the soft start time is different because of constancy depending on the value offset output voltage. When 1V setting it, it is $T_{ss}=1\text{msec(Typ.)}$

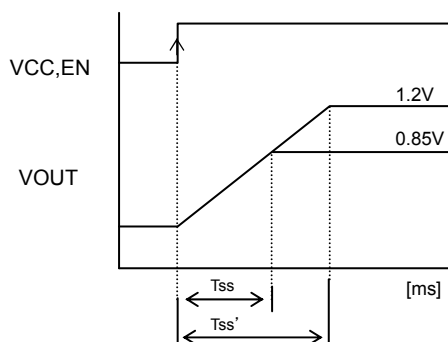


Fig.28 Soft start action

• Shutdown function

With EN terminal shifted to "Low", the device turns to Standby Mode, and all the function blocks including reference voltage circuit, internal oscillator and drivers are turned to OFF. Circuit current during standby is 0μA(Typ.).

• UVLO function

Detects whether the input voltage sufficient to secure the output voltage of this IC is supplied. And the hysteresis width of 50mV (Typ.) is provided to prevent output chattering.

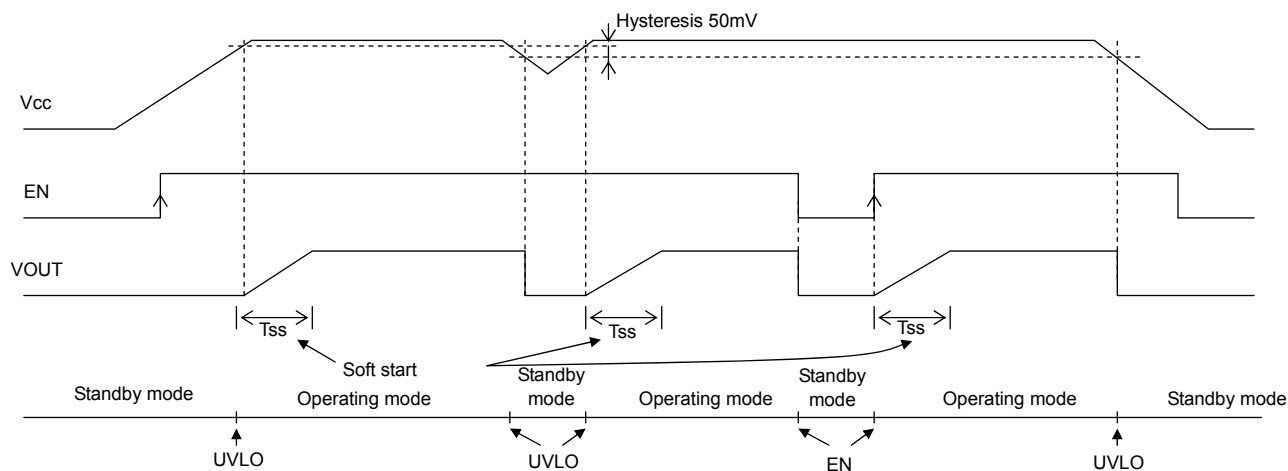


Fig.29 Soft start, Shutdown, UVLO timing chart

• PGOOD function

When the output voltage falls below 75% (Typ.) of a set value, the PGOOD pin of Open-Drain is turned off. And the hysteresis width of 15% (Typ.) is provided to prevent output chattering.

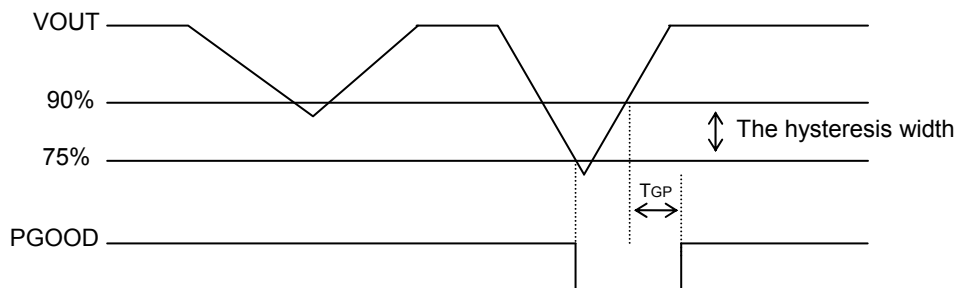
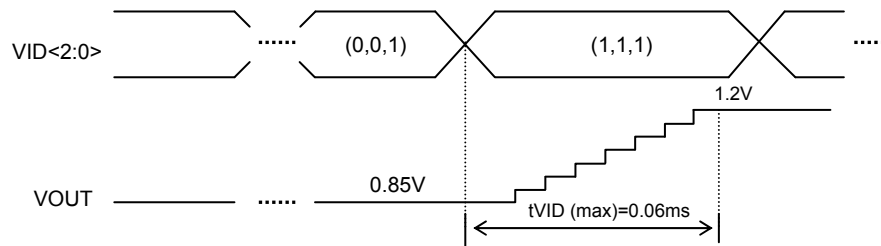


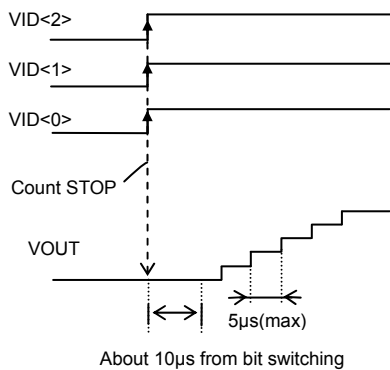
Fig.30 PGOOD timing chart

●About setting the output voltage

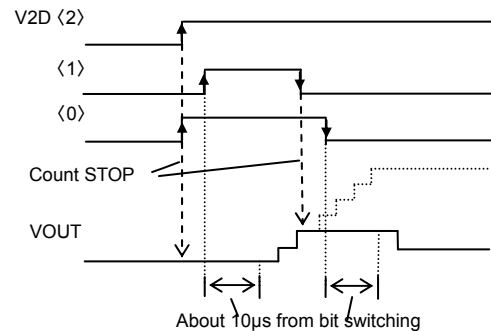
Output voltage shifts step by step as often as bit setting to control the overshoot/undershoot that happen when changing the setting value of output voltage. From the bit switching until output voltage reach to setting value, 8 steps (max) delay will occur.



i) Switching 3 bit synchronously



iii) Switching the bit during counting



ii) Switching 3 bit with the time lag

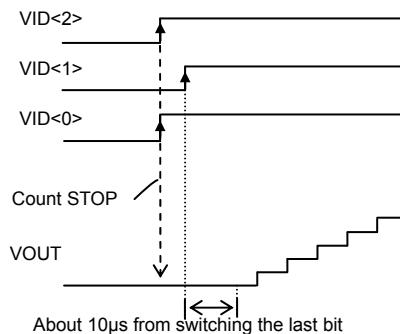


Fig.31 Timing chart of setting the output voltage

It is possible to set output voltage, shown the diagram 1 below, by setting VID<0>~<2> 0 or 1. VID<2:0> terminal is set to VID<2:0>=(0,0,0) originally by the pull down resistor with high impedance inside IC. By pulling up/ pulling down about 10k Ω , the original value is changeable optionally.

Table of output voltage setting

VID<2>	VID<1>	VID<0>	V _{OUT}
0	0	0	1.0V
0	0	1	0.85V
0	1	0	0.9V
0	1	1	0.95V
1	0	0	1.05V
1	0	1	1.1V
1	1	0	1.15V
1	1	1	1.2V

*After 10 μ s(max) from the bit change, V_{OUT} change starts.

*Requiring time for one step (50 mV shift) of V_{OUT} is 5 μ s(max).

*From the bit switching until output voltage reach to setting value, tVID(max)=0.06ms delay will occur.

• Short-current protection circuit with time delay function

Turns OFF the output to protect the IC from breakdown when the incorporated current limiter is activated continuously for the fixed time (TLATCH) or more. The output thus held tuned OFF may be recovered by restarting EN or by re-unlocking UVLO.

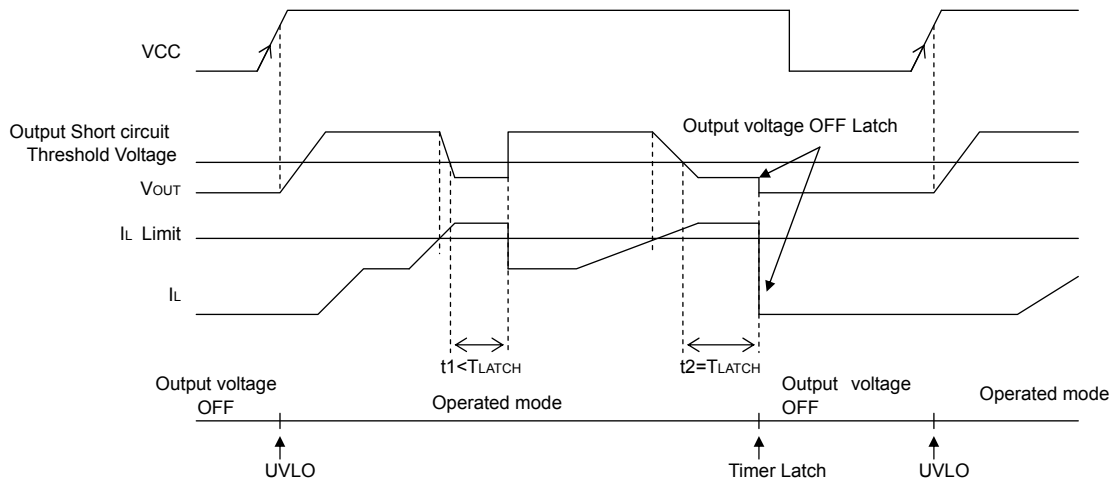


Fig.32 Short-current protection circuit with time delay timing chart

● Switching regulator efficiency

Efficiency η may be expressed by the equation shown below:

$$\eta = \frac{V_{OUT} \times I_{OUT}}{V_{in} \times I_{in}} \times 100[\%] = \frac{P_{OUT}}{P_{in}} \times 100[\%] = \frac{P_{OUT}}{P_{OUT} + P_{D\alpha}} \times 100[\%]$$

Efficiency may be improved by reducing the switching regulator power dissipation factors $P_{D\alpha}$ as follows:

Dissipation factors:

- 1) ON resistance dissipation of inductor and FET: $PD(I^2R)$
- 2) Gate charge/discharge dissipation: $PD(\text{Gate})$
- 3) Switching dissipation: $PD(\text{SW})$
- 4) ESR dissipation of capacitor: $PD(\text{ESR})$
- 5) Operating current dissipation of IC: $PD(\text{IC})$

- 1) $PD(I^2R) = I_{OUT}^2 \times (R_{COIL} + R_{ON})$
($R_{COIL}[\Omega]$: DC resistance of inductor, $R_{ON}[\Omega]$: ON resistance of FET, $I_{OUT}[A]$: Output current.)

- 2) $PD(\text{Gate}) = C_{gs} \times f \times V$
($C_{gs}[F]$: Gate capacitance of FET, $f[H]$: Switching frequency, $V[V]$: Gate driving voltage of FET)

- 3) $PD(\text{SW}) = \frac{V_{in}^2 \times C_{RSS} \times I_{OUT} \times f}{I_{DRIVE}}$
($C_{RSS}[F]$: Reverse transfer capacitance of FET, $I_{DRIVE}[A]$: Peak current of gate.)

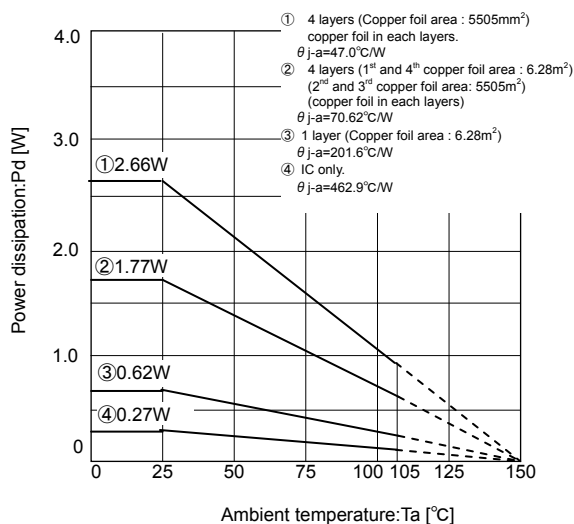
- 4) $PD(\text{ESR}) = I_{RMS}^2 \times ESR$
($I_{RMS}[A]$: Ripple current of capacitor, $ESR[\Omega]$: Equivalent series resistance.)

- 5) $PD(\text{IC}) = V_{in} \times I_{CC}$
($I_{CC}[A]$: Circuit current.)

●Consideration on permissible dissipation and heat generation

As this IC functions with high efficiency without significant heat generation in most applications, no special consideration is needed on permissible dissipation or heat generation. In case of extreme conditions, however, including lower input voltage, higher output voltage, heavier load, and/or higher temperature, the permissible dissipation and/or heat generation must be carefully considered.

For dissipation, only conduction losses due to DC resistance of inductor and ON resistance of FET are considered. Because the conduction losses are considered to play the leading role among other dissipation mentioned above including gate charge/discharge dissipation and switching dissipation.



$$P = I_{OUT}^2 \times R_{ON}$$

$$R_{ON} = D \times R_{ONP} + (1-D)R_{ONN}$$

D : ON duty (=V_{OUT}/V_{CC})
 R_{ONP} : ON resistance of Highside MOS FET
 R_{ONN} : ON resistance of Lowside MOS FET
 I_{OUT} : Output current

Fig.33 Thermal derating curve
(VQFN016V3030)

If V_{CC}=3.3V, V_{OUT}=1.2V, R_{ONP}=0.35mΩ, R_{ONN}=0.25mΩ

I_{OUT}=1.2A, for example,

$$D = V_{OUT}/V_{CC} = 1.2/5 = 0.24$$

$$R_{ON} = 0.24 \times 0.35 + (1-0.24) \times 0.25$$

$$= 0.084 + 0.19$$

$$= 0.274[\Omega]$$

$$P = 1.2^2 \times 0.274 = 0.394[W]$$

As R_{ONP} is greater than R_{ONN} in this IC, the dissipation increases as the ON duty becomes greater. With the consideration on the dissipation as above, thermal design must be carried out with sufficient margin allowed.

● Selection of components externally connected

1. Selection of inductor (L)

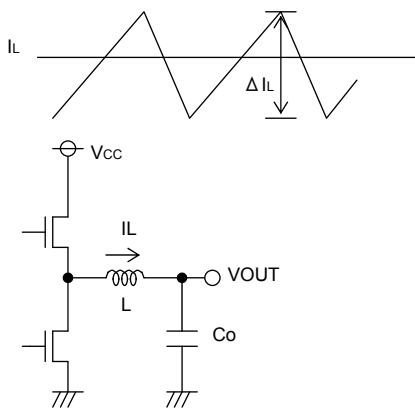


Fig.34 Output ripple current

The inductance significantly depends on output ripple current. As seen in the equation (1), the ripple current decreases as the inductor and/or switching frequency increases.

$$\Delta I_L = \frac{(V_{CC} - V_{OUT}) \times V_{OUT}}{L \times V_{CC} \times f} [A] \dots (1)$$

Appropriate ripple current at output should be 20% more or less of the maximum output current.

$$\Delta I_L = 0.3 \times I_{OUTmax} [A] \dots (2)$$

$$L = \frac{(V_{CC} - V_{OUT}) \times V_{OUT}}{\Delta I_L \times V_{CC} \times f} [H] \dots (3)$$

(ΔI_L : Output ripple current, and f : Switching frequency)

※Current exceeding the current rating of the inductor results in magnetic saturation of the inductor, which decreases efficiency. The inductor must be selected allowing sufficient margin with which the peak current may not exceed its current rating.

If $V_{CC}=5.0V$, $V_{OUT}=1.2V$, $f=1MHz$, $\Delta I_L=0.3 \times 1.2A=0.36A$, for example,

$$L = \frac{(5-1.2) \times 1.2}{0.6 \times 5 \times 1M} = 2.53\mu \rightarrow 4.7 [\mu H]$$

※Select the inductor of low resistance component (such as DCR and ACR) to minimize dissipation in the inductor for better efficiency.

2. Selection of output capacitor (Co)

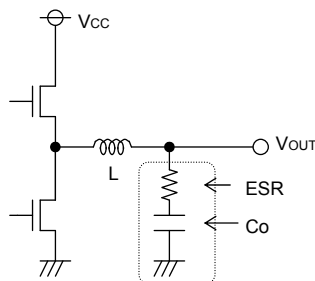


Fig.35 Output capacitor

Output capacitor should be selected with the consideration on the stability region and the equivalent series resistance required to smooth ripple voltage.

Output ripple voltage is determined by the equation (4):

$$\Delta V_{OUT} = \Delta I_L \times ESR [V] \dots (4)$$

(ΔI_L : Output ripple current, ESR: Equivalent series resistance of output capacitor)

※Rating of the capacitor should be determined allowing sufficient margin against output voltage. A $10\mu F$ to $100\mu F$ ceramic capacitor is recommended.

Less ESR allows reduction in output ripple voltage.

3. Selection of input capacitor (Cin)

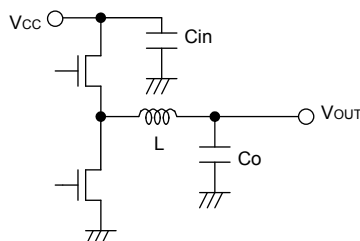


Fig.36 Input capacitor

Input capacitor to select must be a low ESR capacitor of the capacitance sufficient to cope with high ripple current to prevent high transient voltage. The ripple current I_{RMS} is given by the equation (5):

$$I_{RMS} = I_{OUT} \times \frac{\sqrt{V_{OUT}(V_{CC} - V_{OUT})}}{V_{CC}} [A] \dots (5)$$

< Worst case > $I_{RMS(max)}$

$$\text{When } V_{CC} = 2 \times V_{OUT}, I_{RMS} = \frac{I_{OUT}}{2}$$

If $V_{CC}=5V$, $V_{OUT}=1.2V$, and $I_{OUTmax}=1.2A$,

$$I_{RMS} = 1.2 \times \frac{\sqrt{1.2(5-1.2)}}{5} = 0.51 [A_{RMS}]$$

A low ESR $10\mu F/10V$ ceramic capacitor is recommended to reduce ESR dissipation of input capacitor for better efficiency.

4. Determination of RITH, CITH that works as a phase compensator

As the Current Mode Control is designed to limit a inductor current, a pole (phase lag) appears in the low frequency area due to a CR filter consisting of a output capacitor and a load resistance, while a zero (phase lead) appears in the high frequency area due to the output capacitor and its ESR. So, the phases are easily compensated by adding a zero to the power amplifier output with C and R as described below to cancel a pole at the power amplifier.

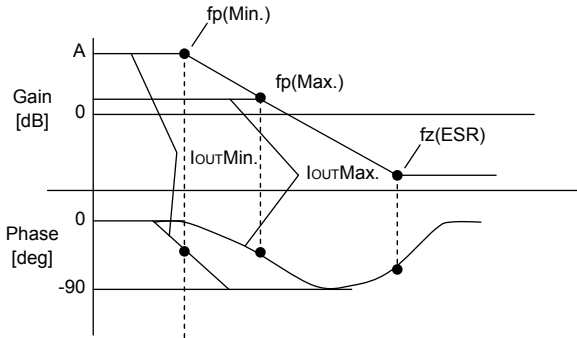


Fig.37 Open loop gain characteristics

$$f_p = \frac{1}{2\pi \times R_o \times C_o}$$

$$f_z(\text{ESR}) = \frac{1}{2\pi \times \text{ESR} \times C_o}$$

Pole at power amplifier

When the output current decreases, the load resistance R_o increases and the pole frequency lowers.

$$f_p(\text{Min.}) = \frac{1}{2\pi \times R_{o\text{Max.}} \times C_o} \text{ [Hz]} \leftarrow \text{with lighter load}$$

$$f_p(\text{Max.}) = \frac{1}{2\pi \times R_{o\text{Min.}} \times C_o} \text{ [Hz]} \leftarrow \text{with heavier load}$$

Zero at power amplifier

Increasing capacitance of the output capacitor lowers the pole frequency while the zero frequency does not change. (This is because when the capacitance is doubled, the capacitor ESR reduces to half.)

$$f_z(\text{Amp.}) = \frac{1}{2\pi \times R_{\text{ITH}} \times C_{\text{ITH}}}$$

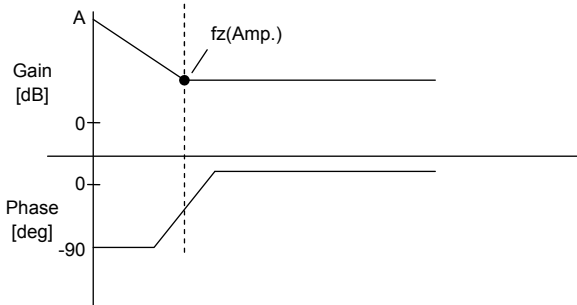


Fig.38 Error amp phase compensation characteristics

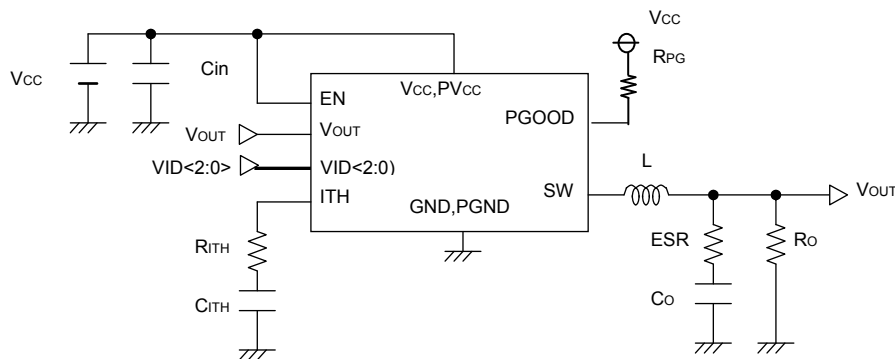


Fig.39 Typical application

Stable feedback loop may be achieved by canceling the pole $f_p(\text{Min.})$ produced by the output capacitor and the load resistance with CR zero correction by the error amplifier.

$$f_z(\text{Amp.}) = f_p(\text{Min.})$$

$$\rightarrow \frac{1}{2\pi \times R_{\text{ITH}} \times C_{\text{ITH}}} = \frac{1}{2\pi \times R_{o\text{Max.}} \times C_o}$$

●Cautions on PC Board layout

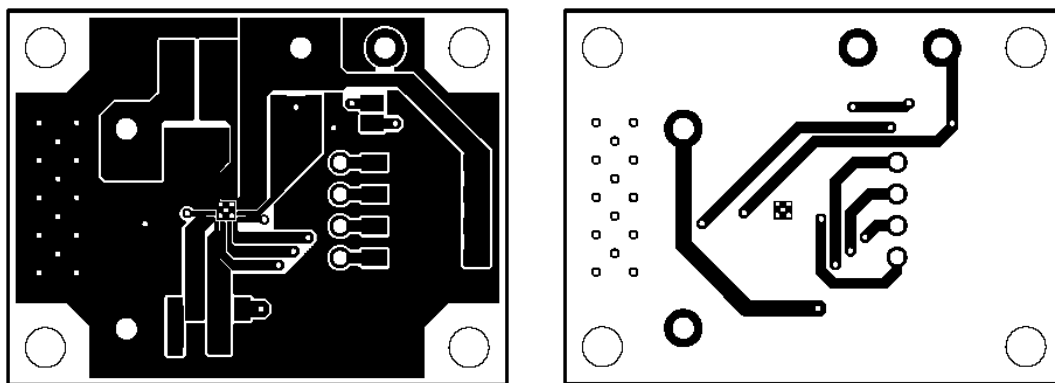


Fig.40 Layout diagram

- ① Lay out the input ceramic capacitor C_{IN} closer to the pins PVCC and PGND, and the output capacitor C_o closer to the pin PGND.
- ② Lay out C_{ITH} and R_{ITH} between the pins ITH and GND as neat as possible with least necessary wiring.

※VQFN016V3030 has thermal PAD on the reverse of the package.

The package thermal performance may be enhanced by bonding the PAD to GND plane which take a large area of PCB.

●Recommended components Lists on above application

Recommended components Lists

Symbol	Part	Value	Manufacturer	Series
L	Coil	4.7uH	TDK	VLF5014S-4R7M1R7
C _{IN}	Ceramic capacitor	10uF	KYOCERA	CM316X5R106M10A
C _o	Ceramic capacitor	22uF	KYOCERA	CM316B226M06A
C _{ITH}	Ceramic capacitor	1500pF	murata	GRM18 Series
R _{ITH}	Resistance	9.1kΩ	ROHM	MCR03 Series
C _f	Ceramic capacitor	0.1uF	murata	GRM18 Series
R _f	Resistance	100Ω	ROHM	MCR03 Series

※The parts list presented above is an example of recommended parts. Although the parts are sound, actual circuit characteristics should be checked on your application carefully before use. Be sure to allow sufficient margins to accommodate variations between external devices and this IC when employing the depicted circuit with other circuit constants modified. Both static and transient characteristics should be considered in establishing these margins. When switching noise is substantial and may impact the system, a low pass filter should be inserted between the VCC and PVCC pins, and a schottky barrier diode or snubber established between the SW and PGND pins.

● I/O equivalence circuit
【BD9123MUV】

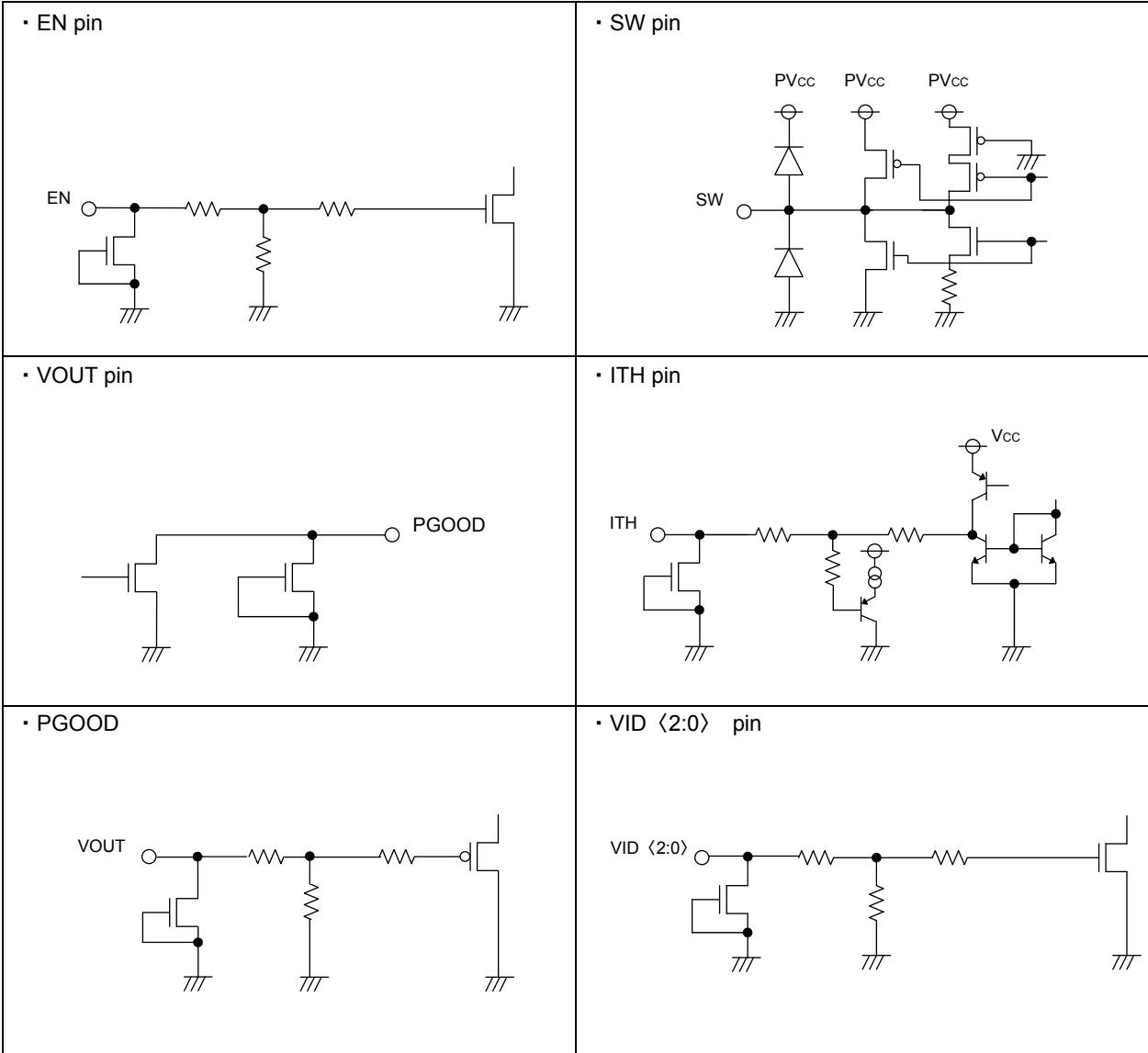


Fig.41 I/O equivalence circuit

●Notes for use

1. Absolute Maximum Ratings

While utmost care is taken to quality control of this product, any application that may exceed some of the absolute maximum ratings including the voltage applied and the operating temperature range may result in breakage. If broken, short-mode or open-mode may not be identified. So if it is expected to encounter with special mode that may exceed the absolute maximum ratings, it is requested to take necessary safety measures physically including insertion of fuses.

2. Electrical potential at GND

GND must be designed to have the lowest electrical potential in any operating conditions.

3. Short-circuiting between terminals, and mismounting

When mounting to pc board, care must be taken to avoid mistake in its orientation and alignment. Failure to do so may result in IC breakdown. Short-circuiting due to foreign matters entered between output terminals, or between output and power supply or GND may also cause breakdown.

4. Thermal shutdown protection circuit

Thermal shutdown protection circuit is the circuit designed to isolate the IC from thermal runaway, and not intended to protect and guarantee the IC. So, the IC the thermal shutdown protection circuit of which is once activated should not be used thereafter for any operation originally intended.

5. Inspection with the IC set to a pc board

If a capacitor must be connected to the pin of lower impedance during inspection with the IC set to a pc board, the capacitor must be discharged after each process to avoid stress to the IC. For electrostatic protection, provide proper grounding to assembling processes with special care taken in handling and storage. When connecting to jigs in the inspection process, be sure to turn OFF the power supply before it is connected and removed.

6. Input to IC terminals

This is a monolithic IC with P⁺ isolation between P-substrate and each element as illustrated below. This P-layer and the N-layer of each element form a P-N junction, and various parasitic elements are formed.

If a resistor is joined to a transistor terminal as shown in Fig 42.

OP-N junction works as a parasitic diode if the following relationship is satisfied; GND>Terminal A (at resistor side), or GND>Terminal B (at transistor side); and

Of GND>Terminal B (at NPN transistor side),

a parasitic NPN transistor is activated by N-layer of other element adjacent to the above-mentioned parasitic diode.

The structure of the IC inevitably forms parasitic elements, the activation of which may cause interference among circuits, and/or malfunctions contributing to breakdown. It is therefore requested to take care not to use the device in such manner that the voltage lower than GND (at P-substrate) may be applied to the input terminal, which may result in activation of parasitic elements.

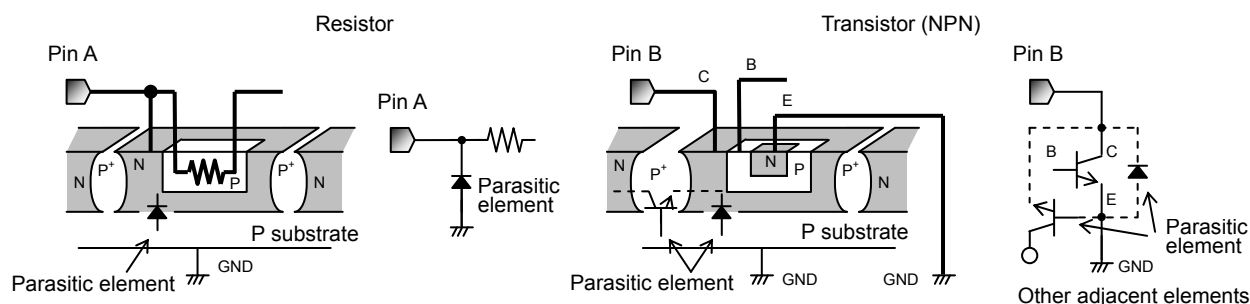


Fig.42 Simplified structure of monoristic IC

7. Ground wiring pattern

If small-signal GND and large-current GND are provided, It will be recommended to separate the large-current GND pattern from the small-signal GND pattern and establish a single ground at the reference point of the set PCB so that resistance to the wiring pattern and voltage fluctuations due to a large current will cause no fluctuations in voltages of the small-signal GND. Pay attention not to cause fluctuations in the GND wiring pattern of external parts as well.

8. Selection of inductor

It is recommended to use an inductor with a series resistance element (DCR) 50mΩ or less. Especially, in case output voltage is set 1.6V or more, note that use of a high DCR inductor will cause an inductor loss, resulting in decreased output voltage. Should this condition continue for a specified period (soft start time + timer latch time), output short circuit protection will be activated and output will be latched OFF. When using an inductor over 50mΩ, be careful to ensure adequate margins for variation between external devices and this IC, including transient as well as static characteristics. Furthermore, in any case, it is recommended to start up the output with EN after supply voltage is within operation range.

●Ordering part number

B	D
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Part No.

9	1	2	3
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Part No.

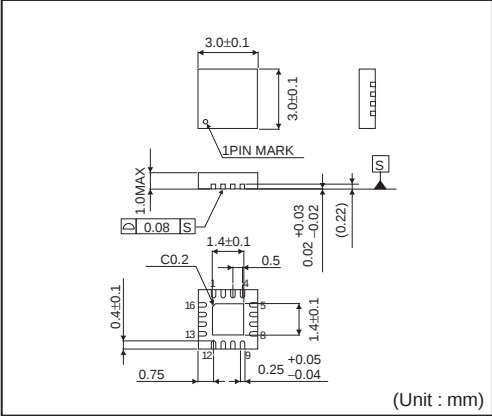
M	U	V
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Package
MUV : VQFN016V3030

E	2
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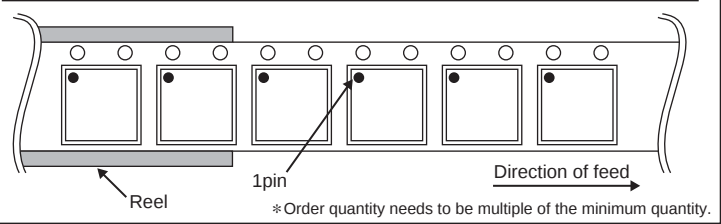
Packaging and forming specification
E2: Embossed tape and reel

VQFN016V3030



<Tape and Reel information>

Tape	Embossed carrier tape
Quantity	3000pcs
Direction of feed	E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)



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